



A semiconductor device X1 comprises: a first conductor 110 including a first terminal surface 113a; a second conductor 120 placed by the first conductor 110 and including a second terminal surface 123a facing a same direction as does the first terminal surface 113a; a third conductor 130 connected with the first conductor 110; a semiconductor chip 140 including a first surface 141 and a second surface 142 away from the first surface, and bonded to the first conductor 110 and to the second conductor 120 via the second surface 142; and a resin package 150. The first surface 141 of the semiconductor chip 140 is provided with a first electrode electrically connected with the first conductor 110 via the third conductor 130. The second surface 142 is provided with a second electrode electrically connected directly with the second conductor 120. The resin package 150 seals the first conductor 110, the second conductor 120, the third conductor 130 and the semiconductor chip 140 while exposing the first terminal surface 113a and the second terminal surface 123a.